

		Specification (Revisions)		Type CEP1311
Symbol	Date	Issue No.	Revisions	Client
△	20th. Apr. , 2009	PD16-09-399	Construction Dimension Dimension of pin:0.65±0.2 deleted(P.2/3)	C-Lab King Liu

Note :	Spec. No. S-0074-6658 1/3
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# Specification

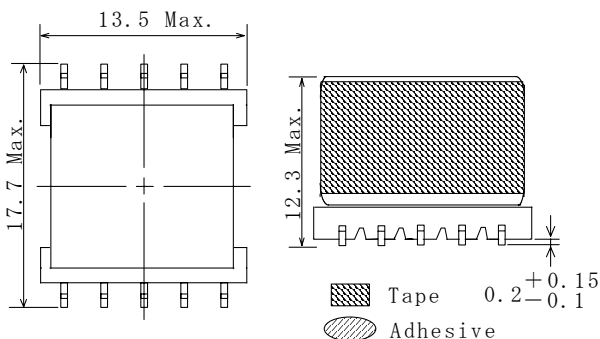
Type CEP1311
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## 1. Scope and general stipulations.

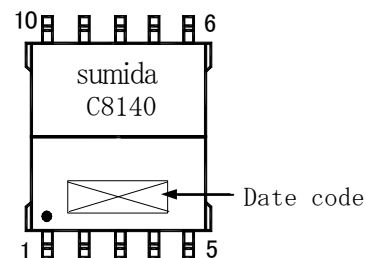
Ref. to S-074-1510.

## 2. Construction

### 2-1. Dimension (mm)



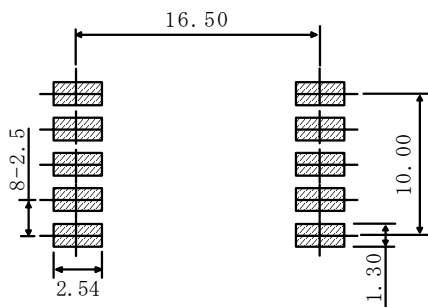
### 2-2. Stamp



\* Dimension does not include solder used on coil.

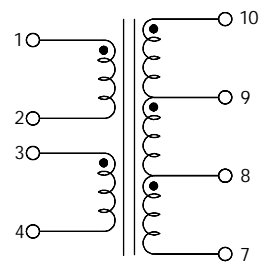
\* Terminals should be measured excluding the length of the soldered point.

### 2-3. Recommended land pattern dimensions (mm)



## 3. Coil specification

### 3-1. Connection (Bottom view)



“●” is winding start.

<p><b>RoHS</b> compliance Cd:Max. 0.01wt% others:Max. 0.1wt%</p>
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### 3-2. Electrical characteristic

			Measuring conditions
Inductance	(1-4)	4.5 $\mu$ H $\pm$ 10% Within	100kHz, 0.1V (tie 2+3)
Leakage inductance	(1-4)	0.18 $\mu$ H Max.	100kHz, 0.1V (tie 2+3, 7+8+9+10)
D. C. R.	(10-7)	320m $\Omega$ Max.	at 25°C
D. C. R.	(1-4)	45m $\Omega$ Max.	at 25°C (tie 2+3)
Turns ratio	(10-7) : (1-4)	4:1	100kHz, 0.1V (tie 2+3)
Turns ratio	(10-7) : (8-7)	3:1	
Hi-pot	(1, 2, 3, 4-7, 8, 9, 10)	DC 500V	0.5mA 1S.
Hi-pot	(1, 2, 3, 4, 7, 8, 9, 10-Core)	DC 500V	0.5mA 1S.
Operating temperature		-40 to +85°C	

\* Testing equipment HP-4284A or equivalent.

Date: 4 t h. S e p . , 2 0 0 6		Part No.	C 8 1 4 Ø	
Chk.	Chk.	Drg.	SUMIDA code	0 4 3 6 7 0 0 3 8
YU WEIWEN	WEI YANCHUN	HAN LICHENG LSM	Sample No.	4 3 6 7 - T 1 2 4
			First issue	
			Spec. No.	S - 0 0 7 4 - 6 6 5 8 2 / 3

# Specification

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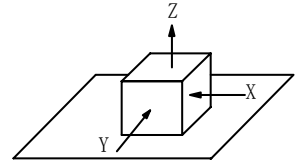
## 4. General characteristics

4-1. Storage temperature range :  $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

4-2. Operating temperature range:  $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$  (Including coil's self temperature rise)

4-3. External appearance : No external defects can be found in the visual inspection.

4-4. Fixing strength : No terminal detachment should be found when the device is pushed in three directions of X, Y and Z with the force of 5.0N for  $60 \pm 5$  seconds after soldering between copper plate and the terminals.  
(Refer to figure at right)



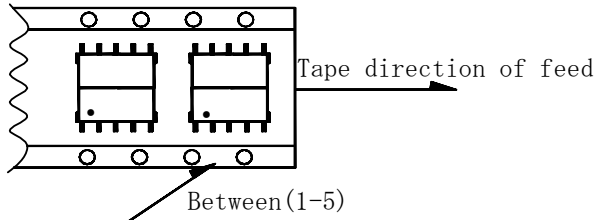
4-5. Heat endurance test : Refer to S-074-1516.

4-6. Recommended reflow condition : Refer to S-074-1518.

4-7. Humidity test : Inductance deviation is within  $\pm 5.0\%$  and no structure and electric defects can be found after  $96 \pm 4$  hours test under the condition of relative humidity of 90~95% and temperature of  $40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , and 1 hour storage under room ambient conditions.

## 5. Packing specification

5-1. Enclosing condition of coils.



5-2. Carrier tape packing specification in detail. (S-074-5174)

Note :

Spec. No.

S-0074-6658

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